

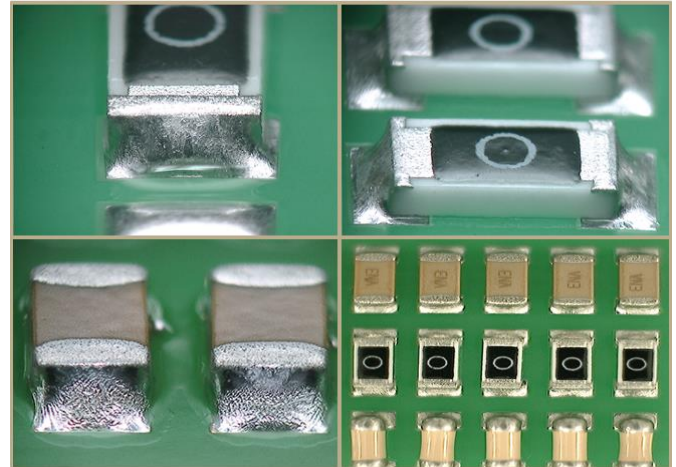
NC258 NO CLEAN SOLDER PASTE

FEATURES

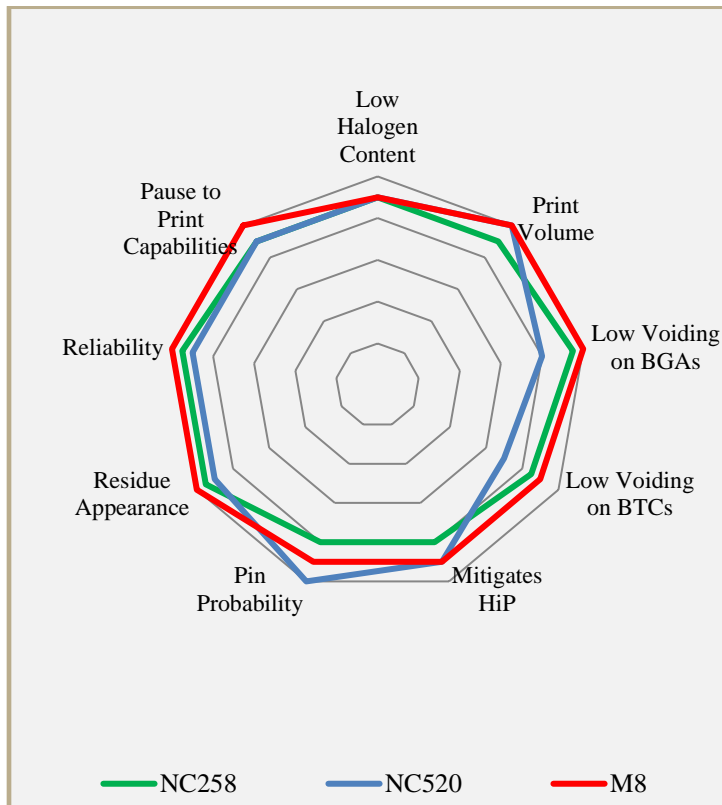
- Long Pause-to-Print Capabilities
- Excellent Wetting, Even Leadless Devices
- Reduces Voiding
- Low Post Process Residues
- RoHS Compliant
- Passes Bono Testing

DESCRIPTION

NC258 has been developed to offer long pause-to-print capabilities while enhancing fine print definitions. NC258 reduces voiding. The superior wetting ability of NC258 results in bright, smooth and shiny solder joints. It also offers very low post process residues, which remain crystal clear even at the elevated temperatures required for today's lead-free alloys.



CHARACTERISTICS



HANDLING & STORAGE

| Parameter | Time | Temperature |
|---------------------------|----------|----------------------|
| Refrigerated Shelf Life | 1 year | 0°C-12°C (32°F-55°F) |
| Unrefrigerated Shelf Life | 3 months | < 25°C (< 77°F) |

Do not add used paste to unused paste. Store used paste separately; keep unused paste tightly sealed with internal plug or end cap in place. See AIM's paste handling guidelines for further information. Alloy and storage conditions may affect shelf life. Please refer to NC258 Certificate of Analysis for product specific information.

CLEANING

Pre-Reflow: AIM DJAW-10 effectively removes NC258 solder paste from stencils while in process. DJAW-10 can be hand applied or used in under stencil wipe equipment. DJAW-10 will not dry NC258 and will enhance transfer properties. Do not over-apply DJAW-10. Do not apply DJAW-10 to stencil topside. Isopropanol (IPA) is not recommended in process, but may be used as a final stencil rinse.

Post-Reflow Flux Residue: NC258 residues can remain on the assembly after reflow and do not require cleaning. Where cleaning is mandated, AIM has worked closely with industry partners to ensure that NC258 residues can be effectively removed with common defluxing agents. Contact AIM for cleaning compatibility information.

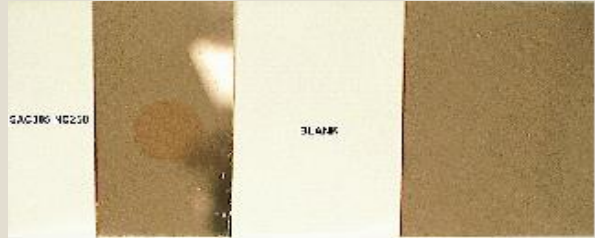


REFLOW PROFILE

Detailed profile information may be found at <http://www.aimsolder.com/reflow-profile-supplements>. Contact AIM for additional information.

PRINTING


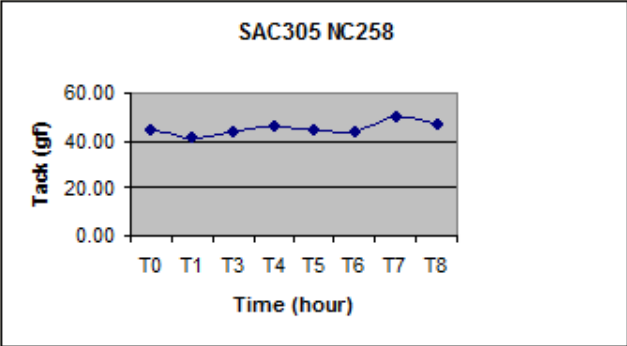
| Recommended Initial Printer Settings - Dependent on PCB and Pad Design | |
|--|------------------------------|
| Parameter | Recommended Initial Settings |
| Squeegee Pressure | 0.9 – 1.5 lbs/inch of blade |
| Squeegee Speed | 0.5 – 6 inches/second |
| Snap-off Distance | On Contact 0.00mm (0.00'') |
| PCB Separation Distance | 0.75 – 2.0mm (.038 - .080'') |
| PCB Separation Speed | 3.0 – 20.00 mm/second |

TEST DATA SUMMARY

| Name | Test Method | Results | |
|-------------------------|---|-----------------|--|
| IPC Flux Classification | J-STD-004 | ROL0 | |
| IPC Flux Classification | J-STD-004B 3.3.1 | ROL1 | |
| Name | Test Method | Typical Results | Image |
| Copper Mirror | J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32 | LOW |  |
| Corrosion | J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15 | PASS | <div style="display: flex; justify-content: space-around;"> <div style="text-align: center;"> <p>Before</p>  </div> <div style="text-align: center;"> <p>After</p>  </div> </div> |

TECHNICAL DATA SHEET

| Name | Test Method | Typical Results | Image |
|---|---|---|--|
| Quantitative Halides, Chloride, Bromide | J-STD-004 3.2.4.3.1 IPC-TM-650 2.3.35 or 28 | Br: 0.33% Cl: 0% | |
| Qualitative Halides, Silver Chromate | J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33 | PASS |  |
| Qualitative Halides, Fluoride Spot | J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1 | No Fluoride | |
| Surface Insulation Resistance | J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7 | PASS See Aim Qualification Test Report #NC258052510 | |
| Bono Testing | | PASS Fc<8.0 Typical | |
| Oxygen Bomb Halogen Testing | EN14582:2007 SW 9056 SW 5050 | Br <50.1 mg/Kg Cl <125 mg/Kg | |
| Electrochemical Migration | J-STD-004B 3.4.1.5 IPC-TM-650 2.6.14.1 | PASS | |
| Flux Solids, Nonvolatile Determination | J-STD-004B 3.4.2.1 IPC-TM-650 2.3.34 | 99.9% Typical | |
| Acid Value Determination | J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13 | 145 +/- 6mg KOH/g Flux Typical | |
| Flux Specific Gravity Determination | J-STD-004B 3.4.2.3 ASTM D-1298 | 0.92 Typical | |
| Viscosity | J-STD-005A 3.5.1 IPC-TM-650 2.4.34 | 600-900 depending on metal load and particle size | |
| Visual | J-STD-004B 3.4.2.5 | PASS | |

| Name | Test Method | Typical Results | Image |
|-------------|-------------------------------------|------------------|---|
| Slump | J-STD-005A 3.6 IPC-TM-650 2.4.35 | PASS | |
| Solder Ball | J-STD-005A 3.7 IPC-TM-650 2.4.43 | PASS |  <p>15Min 4Hr</p> |
| Tack | J-STD-005A 3.8 IPC-TM-650 2.4.44 | 37.9g Typical |  <p>SAC305 NC258</p> <p>Tack (gf)</p> <p>Time (hour)</p> |
| Wetting | J-STD-005A 3.9 IPC-TM-650 2.4.45 | PASS | |

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